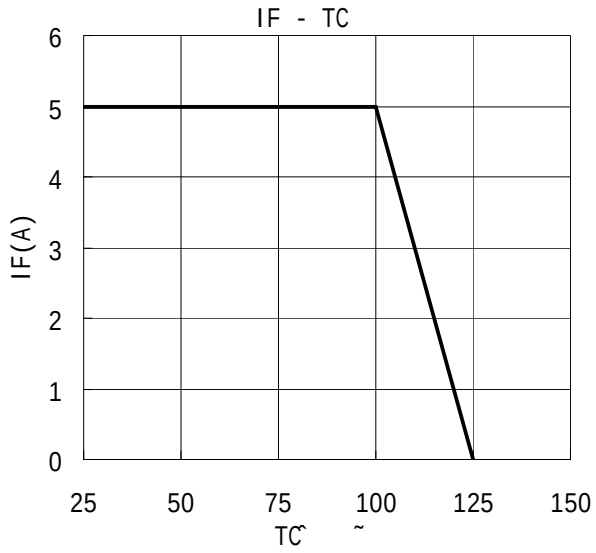
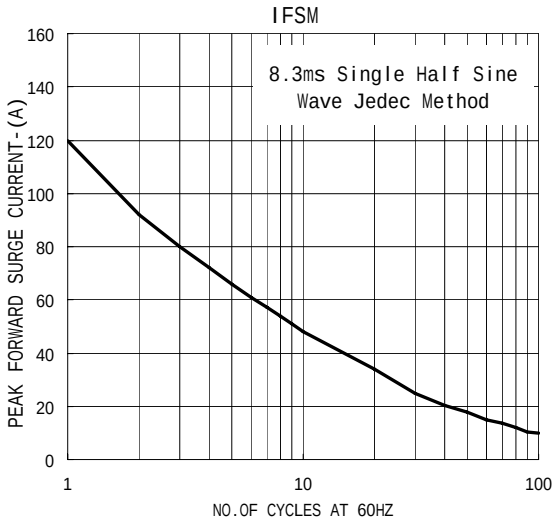
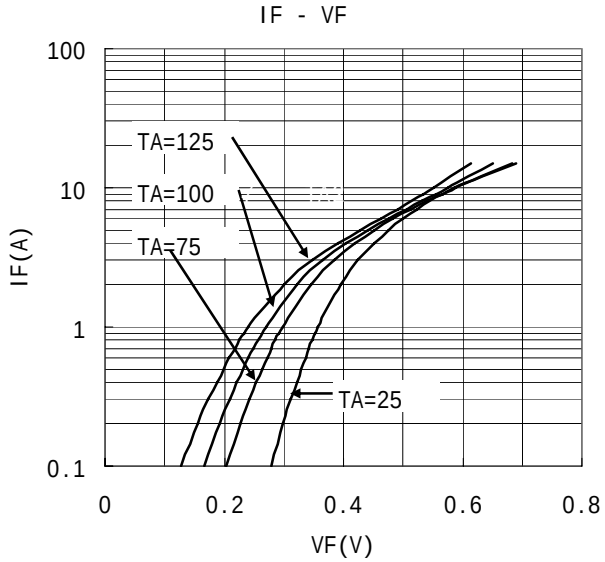
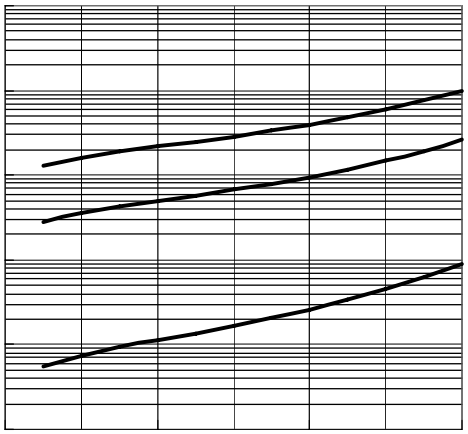
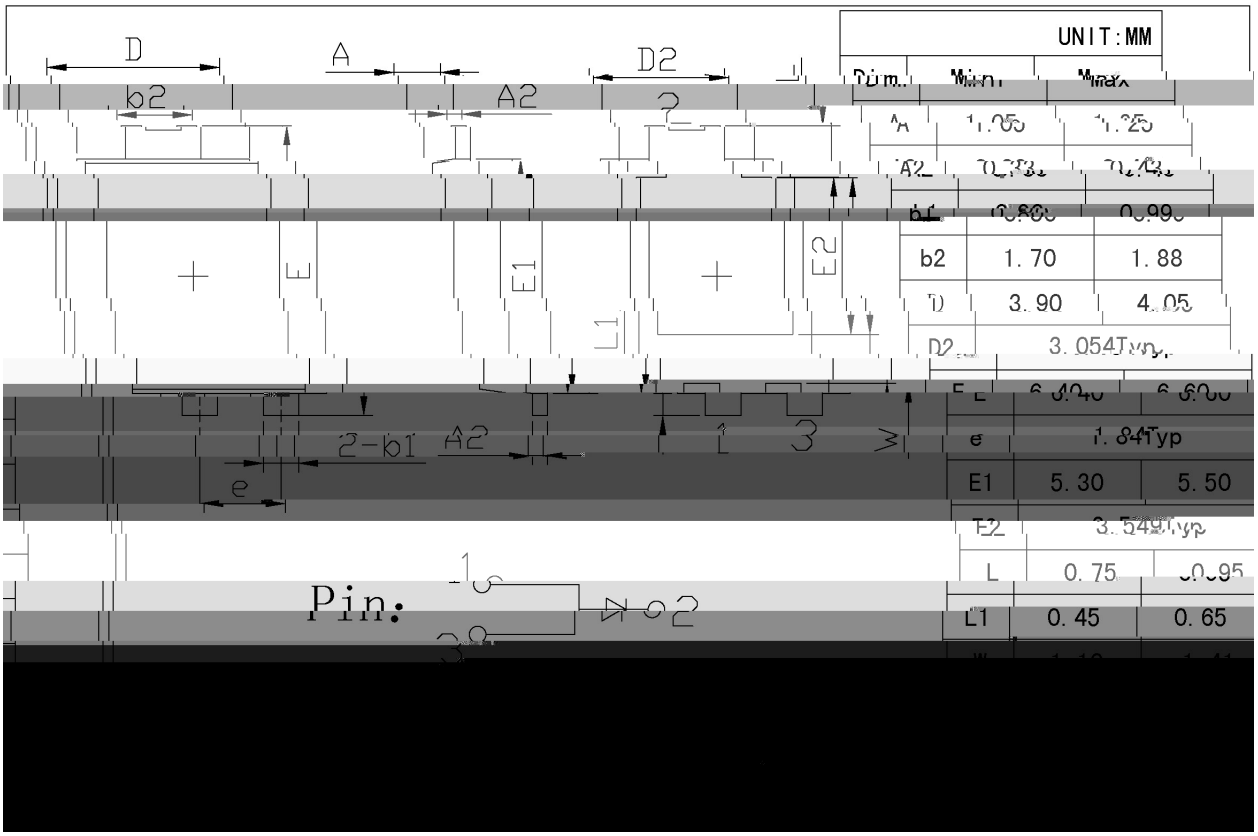

IF - TC
IF(A)
6
5
4
3
2
1
0
25
50
75
100
125
150
TC ~


IFSM
8.3ms Single Half Sine
Wave Jedec Method
PEAK FORWARD SURGE CURRENT-(A)
160
140
120
100
80
60
40
20
0
1
10
100
NO.OF CYCLES AT 60HZ


IF - VF
IF(A)
100
10
1
0.1
TA=125
TA=100
TA=75
TA=25
0
0.2
0.4
0.6
0.8
VF(V)




UNIT:MM
D
A
D2
b2
A2
E
E1
E2
L1
2-b1
e
Pin:
1
2
3
b2 1.70 1.88
D 3.90 4.05
e 1.84Typ
E1 5.30 5.50
L 0.75
L1 0.45 0.65

Temperature Profile for IR Reflow Soldering(Pb-Free)



[redacted]

1	150	180	60	90sec;	
2	245±5			5±0.5sec;	
3		2	10	/sec.	

Note:

1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-277	5,000	3	15,000	6	90,000	13 ×12	360×360×50	380×335×366